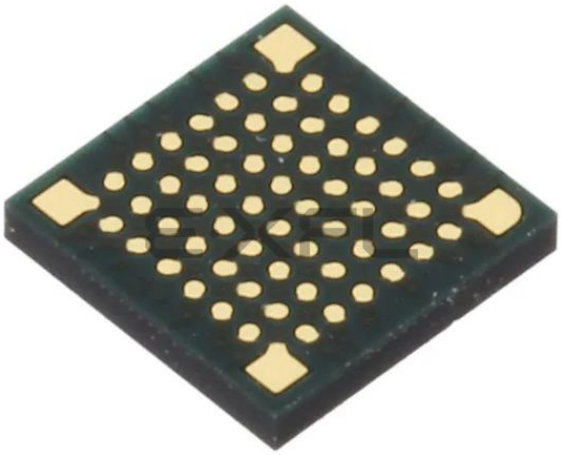

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Details	
Product Status	Active
Core Processor	RX
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I²C, SCI, SPI, USB OTG
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	46
Program Memory Size	96KB (96K x 8)
Program Memory Type	FLASH
EEPROM Size	8K x 8
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 14x12b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-WFLGA
Supplier Device Package	64-FLGA (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f51114adlf-ua

1.3 Block Diagram

Figure 1.2 shows a block diagram.

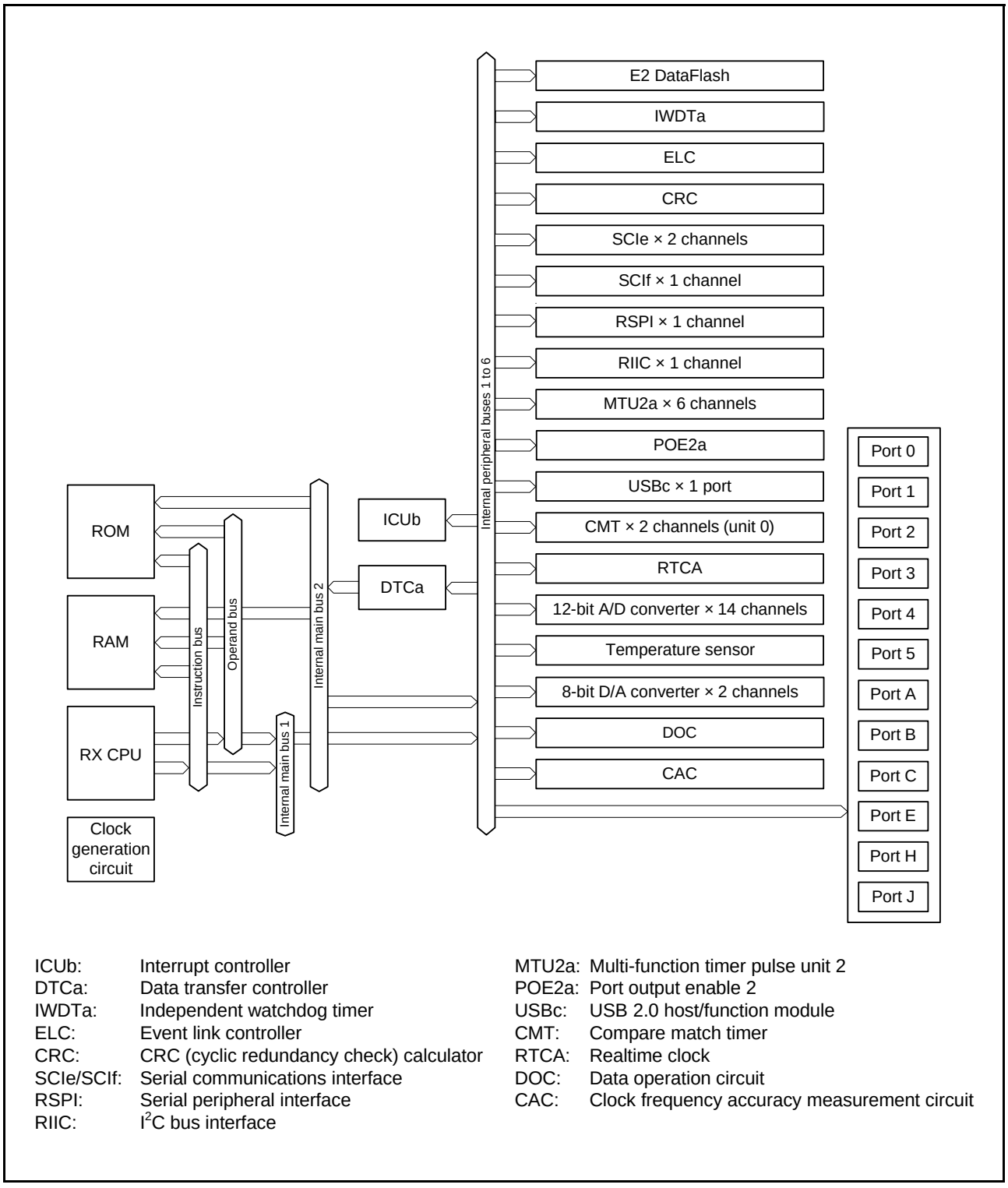


Figure 1.2 Block Diagram

Table 1.4 Pin Functions (2/3)

Classifications	Pin Name	I/O	Description
Realtime clock	RTCOUT	Output	Output pin for the 1-Hz/64-Hz clock.
Serial communications interface (SCIe)	• Asynchronous mode/clock synchronous mode		
	SCK1, SCK5	I/O	Input/output pins for the clock.
	RXD1, RXD5	Input	Input pins for received data.
	TXD1, TXD5	Output	Output pins for transmitted data.
	CTS1#, CTS5#	Input	Input pins for controlling the start of transmission and reception.
	RTS1#, RTS5#	Output	Output pins for controlling the start of transmission and reception.
Serial communications interface (SCIe)	• Simple I^2C mode		
	SSCL1, SSCL5	I/O	Input/output pins for the I^2C clock.
	SSDA1, SSDA5	I/O	Input/output pins for the I^2C data.
	• Simple SPI mode		
	SCK1, SCK5	I/O	Input/output pins for the clock.
	SMISO1, SMISO5	I/O	Input/output pins for slave transmit data.
	SMOSI1, SMOSI5	I/O	Input/output pins for master transmit data.
	SS1#, SS5#	Input	Chip-select input pins.
Serial communications interface (SCIf)	• Asynchronous mode/clock synchronous mode		
	SCK12	I/O	Input/output pin for the clock.
	RXD12	Input	Input pin for receiving data.
	TXD12	Output	Output pin for transmitting data.
	CTS12#	Input	Input pin for controlling the start of transmission and reception.
	RTS12#	Output	Output pin for controlling the start of transmission and reception.
	• Simple I^2C mode		
	SSCL12	I/O	Input/output pin for the I^2C clock.
	SSDA12	I/O	Input/output pin for the I^2C data.
	• Simple SPI mode		
	SCK12	I/O	Input/output pin for the clock.
	SMISO12	I/O	Input/output pin for slave transmit data.
	SMOSI12	I/O	Input/output pin for master transmit data.
	SS12#	Input	Chip-select input pin.
	• Extended serial mode		
	RXDX12	Input	Input pin for data reception by SCIf.
	TXDX12	Output	Output pin for data transmission by SCIf.
	SIOX12	I/O	Input/output pin for data reception or transmission by SCIf.
I^2C bus interface	SCL0	I/O	Input/output pin for I^2C bus interface clocks. Bus can be directly driven by the N-channel open drain output.
	SDA0	I/O	Input/output pin for I^2C bus interface data. Bus can be directly driven by the N-channel open drain output.
Serial peripheral interface	RSPCKA	I/O	Input/output pin for the RSPI clock.
	MOSIA	I/O	Input/output pin for transmitting data from the RSPI master.
	MISOA	I/O	Input/output pin for transmitting data from the RSPI slave.
	SSLA0	I/O	Input/output pin to select the slave for the RSPI.
	SSLA1 to SSLA3	Output	Output pins to select the slave for the RSPI.

Table 1.8 List of Pins and Pin Functions (40-Pin HWQFN) (2/2)

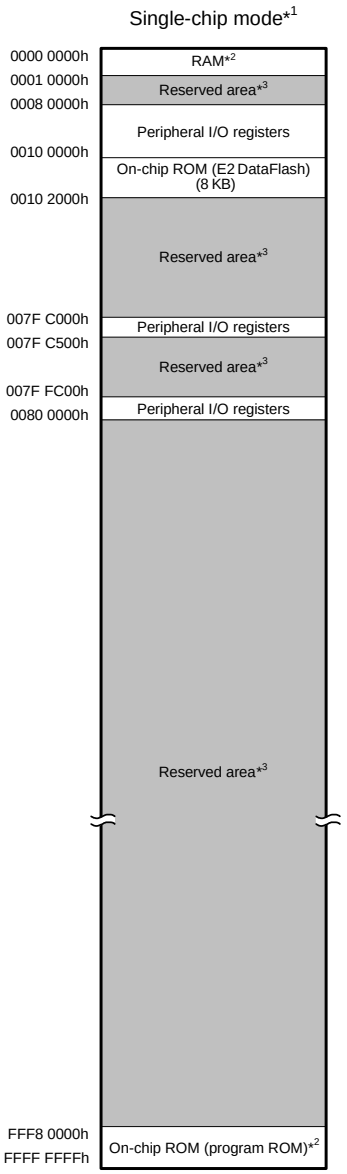
Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, POE, RTC)	Communication (SCIe, SCIf, RSPI, RIIC, USB)	Others
40	AVCC0				

Note 1. Not 5 V tolerant.
Note 2. The power source of the I/O buffer for these pins is AVCC0.

Table 1.9 List of Pins and Pin Functions (36-Pin WFLGA)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, POE, RTC)	Communication (SCIe, SCIf, RSPI, RIIC, USB)	Others
A1	AVSS0				
A2	AVCC0				
A3	VREFH0	PJ6*2			
A4		P42*2			AN002
A5		P41*2			AN001
A6		PE2	MTIOC4A	RXD12/RXDX12/SMISO12/SSCL12	IRQ7/AN010
B1	RES#				
B2		P27	MTIOC2B	SCK1/SCK12	IRQ3/CMPA2/CACREF/ ADTRG0#
B3	VREFL0	PJ7*2			
B4		PE0	MTIOC2A/POE3#	SCK12	IRQ0/AN008
B5		PE1	MTIOC4C	TXD12/TXDX12/SIOX12/SMOSI12/ SSDA12	IRQ1/AN009
B6		PA3	MTIOC0D/MTCLKD/ MTIOC1B/POE0#	RXD5/SMISO5/SSCL5/MISOA	IRQ6
C1	XTAL				
C2	MD				FINED
C3		PE3	MTIOC0A/MTIOC1B/ MTIOC4B/POE8#	CTS12#/RTS12#/SS12#/RSPCKA	IRQ3/AN011
C4		PE4	MTIOC1A/MTIOC3A/ MTIOC4D	MOSIA	IRQ4/AN012
C5		PA4	MTIOC2B/MTIC5U/MTCLKA	TXD5/SMOSI5/SSDA5/SSLA0	IRQ5
C6	VSS				
D1	EXTAL				
D2	UPSEL	P35			NMI
D3	UB#	P14	MTIOC0A/MTIOC3A/ MTCLKA	CTS1#/RTS1#/SS1#/SSLA0/TXD12/ TXDX12/SIOX12/SMOSI12/ SSDA12/USB0_OVRCURA	IRQ4
D4		PA6	MTIC5V/MTCLKB/MTIOC2A/ POE2#	CTS5#/RTS5#/SS5#/SDA0/MOSIA	IRQ3
D5		PB3	MTIOC0A/MTIOC3B/ MTIOC4A/POE3#	USB0_OVRCURA	
D6		PB0	MTIOC0C/MTIC5W	SCL0/RSPCKA	IRQ2/ADTRG0#
E1	VCL				
E2		P17	MTIOC0C/MTIOC3A/ MTIOC3B/POE8#	SCK1/MISOA/SDA0/RXD12/ RXDX12/SMISO12/SSCL12	IRQ7
E3		P16	MTIOC3C/MTIOC3D	TXD1/SMOSI1/SSDA1/SCL0/ MOSIA/USB0_VBUSEN/ USB0_OVRCURB/USB0_VBUS	IRQ6/ADTRG0#
E4		P15	MTIOC0B/MTCLKB	RXD1/SMISO1/SSCL1/RSPCKA	IRQ5/CLKOUT
E5		PC4	MTIOC3D/MTCLKC/POE0#	SCK5/SSLA0/USB0_VBUSEN/ USB0_VBUS*1	IRQ2/CLKOUT
E6	VCC				
F1	VSS				
F2	VCC				
F3	VCC_USB				
F4				USB0_DM	
F5				USB0_DP	
F6	VSS_USB				

Note 1. Not 5 V tolerant.
Note 2. The power source of the I/O buffer for these pins is AVCC0.



Note 1. The address space in boot mode is the same as the address space in single-chip mode.
Note 2. The capacity of ROM/RAM differs depending on the products.

ROM (bytes)		RAM (bytes)	
Capacity	**Address**	**Capacity**	**Address**
512 K	FFF8 0000h to FFFF FFFFh	64 K	0000 0000h to 0000 FFFFh
384 K	FFFA 0000h to FFFF FFFFh		
256 K	FFFC 0000h to FFFF FFFFh	32 K	0000 0000h to 0000 7FFFh
128 K	FFFE 0000h to FFFF FFFFh		
96 K	FFFE 8000h to FFFF FFFFh	16 K	0000 0000h to 0000 3FFFh
64 K	FFFF 0000h to FFFF FFFFh		
32 K	FFFF 8000h to FFFF FFFFh	10 K	0000 0000h to 0000 27FFh
16 K	FFFF C000h to FFFF FFFFh	8 K	0000 0000h to 0000 1FFFh

Note:See Table 1.3, List of Products, for the product type name.

Note 3. Reserved areas should not be accessed.

Figure 3.1 Memory Map

Table 4.1 List of I/O Registers (Address Order) (2/16)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access States
0008 7026h	ICU	Interrupt Request Register 038	IR038	8	8	2 ICLK
0008 702Ch	ICU	Interrupt Request Register 044	IR044	8	8	2 ICLK
0008 702Dh	ICU	Interrupt Request Register 045	IR045	8	8	2 ICLK
0008 702Eh	ICU	Interrupt Request Register 046	IR046	8	8	2 ICLK
0008 702Fh	ICU	Interrupt Request Register 047	IR047	8	8	2 ICLK
0008 7039h	ICU	Interrupt Request Register 057	IR057	8	8	2 ICLK
0008 703Fh	ICU	Interrupt Request Register 063	IR063	8	8	2 ICLK
0008 7040h	ICU	Interrupt Request Register 064	IR064	8	8	2 ICLK
0008 7041h	ICU	Interrupt Request Register 065	IR065	8	8	2 ICLK
0008 7042h	ICU	Interrupt Request Register 066	IR066	8	8	2 ICLK
0008 7043h	ICU	Interrupt Request Register 067	IR067	8	8	2 ICLK
0008 7044h	ICU	Interrupt Request Register 068	IR068	8	8	2 ICLK
0008 7045h	ICU	Interrupt Request Register 069	IR069	8	8	2 ICLK
0008 7046h	ICU	Interrupt Request Register 070	IR070	8	8	2 ICLK
0008 7047h	ICU	Interrupt Request Register 071	IR071	8	8	2 ICLK
0008 7058h	ICU	Interrupt Request Register 088	IR088	8	8	2 ICLK
0008 7059h	ICU	Interrupt Request Register 089	IR089	8	8	2 ICLK
0008 705Ah	ICU	Interrupt Request Register 090	IR090	8	8	2 ICLK
0008 705Ch	ICU	Interrupt Request Register 092	IR092	8	8	2 ICLK
0008 705Dh	ICU	Interrupt Request Register 093	IR093	8	8	2 ICLK
0008 7066h	ICU	Interrupt Request Register 102	IR102	8	8	2 ICLK
0008 7067h	ICU	Interrupt Request Register 103	IR103	8	8	2 ICLK
0008 706Ah	ICU	Interrupt Request Register 106	IR106	8	8	2 ICLK
0008 7072h	ICU	Interrupt Request Register 114	IR114	8	8	2 ICLK
0008 7073h	ICU	Interrupt Request Register 115	IR115	8	8	2 ICLK
0008 7074h	ICU	Interrupt Request Register 116	IR116	8	8	2 ICLK
0008 7075h	ICU	Interrupt Request Register 117	IR117	8	8	2 ICLK
0008 7076h	ICU	Interrupt Request Register 118	IR118	8	8	2 ICLK
0008 7077h	ICU	Interrupt Request Register 119	IR119	8	8	2 ICLK
0008 7078h	ICU	Interrupt Request Register 120	IR120	8	8	2 ICLK
0008 7079h	ICU	Interrupt Request Register 121	IR121	8	8	2 ICLK
0008 707Ah	ICU	Interrupt Request Register 122	IR122	8	8	2 ICLK
0008 707Bh	ICU	Interrupt Request Register 123	IR123	8	8	2 ICLK
0008 707Ch	ICU	Interrupt Request Register 124	IR124	8	8	2 ICLK
0008 707Dh	ICU	Interrupt Request Register 125	IR125	8	8	2 ICLK
0008 707Eh	ICU	Interrupt Request Register 126	IR126	8	8	2 ICLK
0008 707Fh	ICU	Interrupt Request Register 127	IR127	8	8	2 ICLK
0008 7080h	ICU	Interrupt Request Register 128	IR128	8	8	2 ICLK
0008 7081h	ICU	Interrupt Request Register 129	IR129	8	8	2 ICLK
0008 7082h	ICU	Interrupt Request Register 130	IR130	8	8	2 ICLK
0008 7083h	ICU	Interrupt Request Register 131	IR131	8	8	2 ICLK
0008 7084h	ICU	Interrupt Request Register 132	IR132	8	8	2 ICLK
0008 7085h	ICU	Interrupt Request Register 133	IR133	8	8	2 ICLK
0008 7086h	ICU	Interrupt Request Register 134	IR134	8	8	2 ICLK
0008 7087h	ICU	Interrupt Request Register 135	IR135	8	8	2 ICLK
0008 7088h	ICU	Interrupt Request Register 136	IR136	8	8	2 ICLK
0008 7089h	ICU	Interrupt Request Register 137	IR137	8	8	2 ICLK
0008 708Ah	ICU	Interrupt Request Register 138	IR138	8	8	2 ICLK
0008 708Bh	ICU	Interrupt Request Register 139	IR139	8	8	2 ICLK
0008 708Ch	ICU	Interrupt Request Register 140	IR140	8	8	2 ICLK
0008 708Dh	ICU	Interrupt Request Register 141	IR141	8	8	2 ICLK
0008 70AAh	ICU	Interrupt Request Register 170	IR170	8	8	2 ICLK

5.2 DC Characteristics

Table 5.3 DC Characteristics (1)

Conditions: 2.7 V ≤ VCC = VCC_USB ≤ 3.6 V, 2.7 V ≤ AVSS0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Schmitt trigger input voltage	RIIC input pin (except for SMBus, 5 V tolerant)	V_{IH}	VCC × 0.7	—	5.8	V	
	Ports P16, P17, port PA6, port PB0 (5 V tolerant)		VCC × 0.8	—	5.8		
	Ports P03, P05, ports P14,P15, ports P26, P27, ports P30 to P32, P35, ports P54, P55, ports PA0, PA1, PA3, PA4, ports PB1, PB3, PB5 to PB7, ports PC2 to PC7, ports PE0 to PE7, port PH7, RES#		VCC × 0.8	—	VCC + 0.3		
	RIIC input pin (except for SMBus)	V_{IL}	–0.3	—	VCC × 0.3		
	Other than RIIC input pin		–0.3	—	VCC × 0.2		
	RIIC input pin (except for SMBus)	ΔV_T	VCC × 0.05	—	—		
	Other than RIIC input pin		VCC × 0.1	—	—		
Input voltage (except for Schmitt trigger input pins)	MD	V_{IH}	VCC × 0.9	—	VCC + 0.3	V	
	XTAL (external clock input)		VCC × 0.8	—	VCC + 0.3		
	Ports P40 to P44, P46, ports PJ6, PJ7		AVCC0 × 0.7	—	AVCC0 + 0.3		
	RIIC input pin (SMBus)		2.1	—	VCC + 0.3		
	MD	V_{IL}	–0.3	—	VCC × 0.1		
	XTAL (external clock input)		–0.3	—	VCC × 0.2		
	Ports P40 to P44, P46, ports PJ6, PJ7		–0.3	—	AVCC0 × 0.3		
	RIIC input pin (SMBus)		–0.3	—	0.8		

Table 5.4 DC Characteristics (2)

Conditions: 1.8 V ≤ VCC = VCC_USB < 2.7 V, 1.8 V ≤ AVSS0 < 2.7 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Schmitt trigger input voltage	Ports P16, P17, port PA6, port PB0 (5 V tolerant)	V_{IH}	VCC × 0.8	—	5.8	V	
	Ports P03, P05, ports P14,P15, ports P26, P27, ports P30 to P32, P35, ports P54, P55, ports PA0, PA1, PA3, PA4, ports PB1, PB3, PB5 to PB7, ports PC2 to PC7, ports PE0 to PE7, port PH7, RES#		VCC × 0.8	—	VCC + 0.3		
	All pins		–0.3	—	VCC × 0.2		
	All pins	ΔV_T	VCC × 0.01	—	—		
Input voltage (except for Schmitt trigger input pins)	MD	V_{IH}	VCC × 0.9	—	VCC + 0.3	V	
	XTAL (external clock input)		VCC × 0.8	—	VCC + 0.3		
	Ports P40 to P44, P46, ports PJ6, PJ7		AVCC0 × 0.7	—	AVCC0 + 0.3		
	MD	V_{IL}	–0.3	—	VCC × 0.1		
	XTAL (external clock input)		–0.3	—	VCC × 0.2		
	Ports P40 to P44, P46, ports PJ6, PJ7		–0.3	—	AVCC0 × 0.3		

Table 5.5 DC Characteristics (3)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVSS0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Input leakage current	RES#, MD, port P35, port PH7	$\lvert I_{in} \rvert$	—	—	1.0	µA	V_{in} = 0 V, VCC
Three-state leakage current (off-state)	Ports for 5 V tolerant	$\lvert I_{TSI} \rvert$	—	—	1.0	µA	V_{in} = 0 V, 5.8 V
	Pins other than above		—	—	1.0		V_{in} = 0 V, VCC
Input capacitance	All input pins (except for port P16, port P35, USB0_DM, USB0_DP)	C_{in}	—	—	15	pF	V_{in} = 0 mV, Frequency: 1 MHz, T_a = 25°C
	Port P16, port P35, USB0_DM, USB0_DP		—	—	30		

Table 5.6 DC Characteristics (4)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVSS0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Input pull-up resistor	All ports (except for port P35, port PH7)	R_U	10	20	100	kΩ	V_{in} = 0 V

Table 5.8 DC Characteristics (6) (2/2)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVSS0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item					Symbol	Typ *4	Max	Unit	Test Conditions
Supply current*1	Low-speed operating mode	Normal operating mode	No peripheral operation*8	ICLK = 32.768 kHz	I_{CC}	4.3	—	μA	
			All peripheral operation: Normal*9, *10	ICLK = 32.768 kHz		14.7	—		
			All peripheral operation: Max.*9, *10	ICLK = 32.768kHz		—	60		
		Sleep mode	No peripheral operation*8	ICLK = 32.768 kHz		2.2	—		
			All peripheral operation: Normal*9	ICLK = 32.768 kHz		8.3	—		
		Deep sleep mode	No peripheral operation*8	ICLK = 32.768 kHz		1.7	—		
			All peripheral operation: Normal*9	ICLK = 32.768 kHz		6.7	—		

Note 1. Supply current values do not include output charge/discharge current from all pins. The values apply when internal pull-up MOSs are in the off state.
Note 2. Clock supply to the peripheral functions is stopped. This does not include BGO operation. The clock source is PLL. FCLK and PCLK are set to divided by 64.
Note 3. Clocks are supplied to the peripheral functions. This does not include BGO operation. The clock source is PLL. FCLK and PCLK are set to the same frequency as ICLK.
Note 4. Values when VCC = 3.3 V.
Note 5. This is the increase for programming or erasure of the ROM or E2 DataFlash during program execution.
Note 6. Clock supply to the peripheral functions is stopped. The clock source is PLL when ICLK = 12 MHz, and HOCO otherwise. FCLK and PCLK are set to divided by 64.
Note 7. Clocks are supplied to the peripheral functions. The clock source is PLL when ICLK = 12 MHz, and HOCO otherwise. FCLK and PCLK are set to the same frequency as ICLK.
Note 8. Clock supply to the peripheral functions is stopped. The clock source is the sub-clock oscillator. FCLK and PCLK are set to divided by 64.
Note 9. Clocks are supplied to the peripheral functions. The clock source is the sub-clock oscillator. FCLK and PCLK are set to the same frequency as ICLK.
Note 10. Values when the MSTPCRA.MSTPA17 bit (12-bit A/D converter module stop bit) is set to “transition to the module stop state is made”.

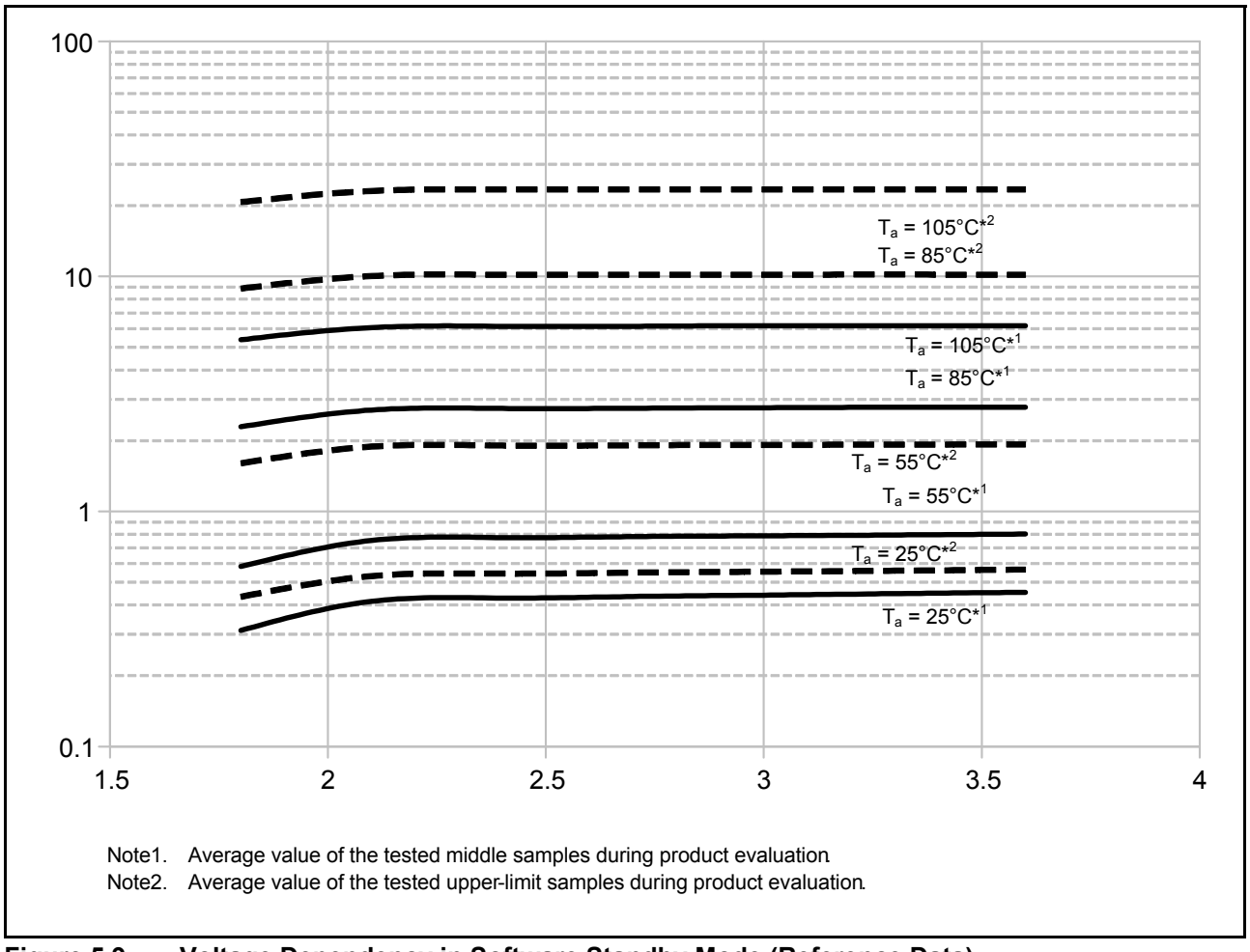
[256-Kbyte or more flash memory]

Table 5.10 DC Characteristics (8)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVSS0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item			Symbol	Typ.*3	Max.	Unit	Test Conditions
Supply current*1	Software standby mode*2	T_a = 25°C	I_{CC}	0.44	0.98	µA	
		T_a = 55°C		0.80	3.47		
		T_a = 85°C		2.7	12.0		
		T_a = 105°C		6.17	42.7		
	Increment for RTC operation*4			0.31	—		RCR3.RTCDV[2:0] = 010b
				1.09	—		RCR3.RTCDV[2:0] = 100b
	Increment for IWDT operation			0.37	—		

Note 1. Supply current values do not include output charge/discharge current from all pins. The values apply when internal pull-up MOSs are in the off state.
Note 2. The IWDT and LVD are stopped.
Note 3. VCC = 3.3 V.
Note 4. Includes the oscillation circuit.



Note1. Average value of the tested middle samples during product evaluation.
Note2. Average value of the tested upper-limit samples during product evaluation.

Figure 5.9 Voltage Dependency in Software Standby Mode (Reference Data)

5.3.3 Timing of Recovery from Low Power Consumption Modes

Table 5.26 Timing of Recovery from Low Power Consumption Modes (1)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVSS0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item				Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Recovery time from software standby mode*1	High-speed mode	Crystal connected to main clock oscillator	Main clock oscillator operating*2	t_{SBYMC}	—	2	3	ms	Figure 5.34
			Main clock oscillator and PLL circuit operating*3	t_{SBYPC}	—	2	3	ms	
		External clock input to main clock oscillator	Main clock oscillator operating*4	t_{SBYEX}	—	35	50	µs	
			Main clock oscillator and PLL circuit operating*5	t_{SBYPE}	—	70	95	µs	
		Sub-clock oscillator operating		t_{SBYSC}	—	650	800	µs	
		HOCO clock oscillator operating*6		t_{SBYHO}	—	40	55	µs	
		LOCO clock oscillator operating		t_{SBYLO}	—	40	55	µs	

Note: When the division ratios of PCLKB, PCLKD, FCLK, and ICLK are all set to 1.

Note 1. The recovery time varies depending on the state of each oscillator when the WAIT instruction is executed. The recovery time when multiple oscillators are operating varies depending on the operating state of the oscillators that are not selected as the system clock source. This applies when only the oscillator listed in each item is operating and the other oscillators are stopped.

Note 2. When the frequency of the crystal is 20 MHz.
When the main clock oscillator wait control register (MOSCWTCR) is set to 04h.

Note 3. When the frequency of PLL is 32 MHz.
When the main clock oscillator wait control register (MOSCWTCR) is set to 04h.

Note 4. When the frequency of the external clock is 20 MHz.
When the main clock oscillator wait control register (MOSCWTCR) is set to 00h.

Note 5. When the frequency of PLL is 32 MHz.
When the main clock oscillator wait control register (MOSCWTCR) is set to 00h.

Note 6. When the frequency of HOCO is 32 MHz.
When the high-speed clock oscillator wait control register (HOCOWTCR) is set to 05h.

5.3.5 Timing of On-Chip Peripheral Modules

Table 5.32 Timing of On-Chip Peripheral Modules (1)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVSS0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item			Symbol	Min.	Max.	Unit*1	Test Conditions
I/O ports	Input data pulse width		t_{PRW}	1.5	—	t_{Pcyc}	Figure 5.38
MTU2	Input capture input pulse width	Single-edge setting	t_{TICW}	1.5	—	t_{Pcyc}	Figure 5.39
		Both-edge setting		2.5	—		
	Timer clock pulse width	Single-edge setting	t_{TCKWH}, t_{TCKWL}	1.5	—	t_{Pcyc}	Figure 5.40
		Both-edge setting		2.5	—		
		Phase counting mode		2.5	—		
POE	POE# input pulse width		t_{POEW}	1.5	—	t_{Pcyc}	Figure 5.41
SCI	Input clock cycle	Asynchronous	t_{Scyc}	4	—	t_{Pcyc}	Figure 5.42
		Clock synchronous		6	—		
	Input clock pulse width		t_{SCKW}	0.4	0.6	t_{Scyc}	
	Input clock rise time		t_{SCKr}	—	20	ns	
	Input clock fall time		t_{SCKf}	—	20	ns	
	Output clock cycle	Asynchronous	t_{Scyc}	16	—	t_{Pcyc}	Figure 5.43 C = 30 pF
		Clock synchronous		4	—		
	Output clock pulse width		t_{SCKW}	0.4	0.6	t_{Scyc}	
	Output clock rise time		t_{SCKr}	—	20	ns	
	Output clock fall time		t_{SCKf}	—	20	ns	
	Transmit data delay time (master)	Clock synchronous	t_{TXD}	—	40	ns	
	Transmit data delay time (slave)	Clock synchronous, 2.7 V or above		—	65	ns	
		Clock synchronous, 1.8 V or above		—	100	ns	
	Receive data setup time (master)	Clock synchronous, 2.7 V or above	t_{RXS}	65	—	ns	
		Clock synchronous, 1.8 V or above		90	—	ns	
	Receive data setup time (slave)	Clock synchronous		40	—	ns	
	Receive data hold time	Clock synchronous	t_{RXH}	40	—	ns	
A/D converter	Trigger input pulse width		t_{TRGW}	1.5	—	t_{Pcyc}	Figure 5.44
CAC	CACREF input pulse width	$t_{Pcyc} \le t_{cac}$*2	t_{CACREF}	4.5 t_{cac} + 3 t_{Pcyc}	—	ns	
		$t_{Pcyc} > t_{cac}$*2		5 t_{cac} + 6.5 t_{Pcyc}			
CLKOUT	CLKOUT pin output cycle*4	VCC = 2.7 V or above	t_{Ccyc}	125	—	ns	
		VCC = 1.8 V or above		250			
	CLKOUT pin high pulse width*3	VCC = 2.7 V or above	t_{CH}	35	—	ns	
		VCC = 1.8 V or above		70			
	CLKOUT pin low pulse width*3	VCC = 2.7 V or above	t_{CL}	35	—	ns	
		VCC = 1.8 V or above		70			
	CLKOUT pin output rise time	VCC = 2.7 V or above	t_{Cr}	—	15	ns	
		VCC = 1.8 V or above			30		
	CLKOUT pin output fall time	VCC = 2.7 V or above	t_{Cf}	—	15	ns	
		VCC = 1.8 V or above			30		

Note 1. t_{Pcyc}: PCLK cycle
Note 2. t_{cac}: CAC count clock source cycle
Note 3. When the LOCO is selected as the clock output source (CKOCR.CKOSEL[2:0] bits = 000b), set the clock output division ratio selection to divided by 2 (CKOCR.CKODIV[2:0] bits = 001b).
Note 4. When the XTAL external clock input or an oscillator is used with divided by 1 (CKOCR.CKOSEL[2:0] bits = 010b and CKOCR.CKODIV[2:0] bits = 000b) to output from CLKOUT, the above should be satisfied with an input duty cycle of 45 to 55%.

Table 5.33 Timing of On-Chip Peripheral Modules (2)

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVSS0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V,
T_a = –40 to +105°C, C = 30 pF

Item				Symbol	Min.	Max.	Unit	Test Conditions
RSPI	RSPCK clock cycle	Master		t_{SPcyc}	2	4096	t_{Pcyc} *1	Figure 5.46
		Slave			8	4096		
	RSPCK clock high pulse width	Master		t_{SPCKWH}	$(t_{SPcyc} - t_{SPCKr} - t_{SPCKf})/2 - 3$	—	ns	
		Slave			$(t_{SPcyc} - t_{SPCKr} - t_{SPCKf})/2$	—		
	RSPCK clock low pulse width	Master		t_{SPCKWL}	$(t_{SPcyc} - t_{SPCKr} - t_{SPCKf})/2 - 3$	—	ns	
		Slave			$(t_{SPcyc} - t_{SPCKr} - t_{SPCKf})/2$	—		
	RSPCK clock rise/fall time	Output	2.7 V or above	t_{SPCKr}, t_{SPCKf}	—	10	ns	
			1.8 V or above		—	15		
		Input			—	1	µs	
	Data input setup time	Master	2.7 V or above	t_{SU}	10	—	ns	Figure 5.47 to Figure 5.52
			1.8 V or above		30	—		
		Slave			$25 - t_{Pcyc}$	—		
	Data input hold time	Master	RSPCK set to a division ratio other than PCLKB divided by 2	t_H	t_{Pcyc}	—	ns	
			RSPCK set to PCLKB divided by 2	t_{HF}	0	—		
		Slave		t_H	$20 + 2 \times t_{Pcyc}$	—		
	SSL setup time	Master		t_{LEAD}	$-30 + N^{*2} \times t_{SPcyc}$	—	ns	
		Slave			2	—	t_{Pcyc}	
	SSL hold time	Master		t_{LAG}	$-30 + N^{*3} \times t_{SPcyc}$	—	ns	
		Slave			2	—	t_{Pcyc}	
	Data output delay time	Master	2.7 V or above	t_{OD}	—	14	ns	
			1.8 V or above		—	30		
		Slave	2.7 V or above		—	$3 \times t_{Pcyc} + 65$		
			1.8 V or above		—	$3 \times t_{Pcyc} + 105$		
	Data output hold time	Master	2.7 V or above	t_{OH}	0	—	ns	
			1.8 V or above		–20	—		
		Slave			0	—		
	Successive transmission delay time	Master		t_{TD}	$t_{SPcyc} + 2 \times t_{Pcyc}$	$8 \times t_{SPcyc} + 2 \times t_{Pcyc}$	ns	
		Slave			$4 \times t_{Pcyc}$	—		
	MOSI and MISO rise/fall time	Output	2.7 V or above	t_{Dr}, t_{Df}	—	10	ns	
			1.8 V or above		—	20		
		Input			—	1	µs	
	SSL rise/fall time	Output		t_{SSLr}, t_{SSLf}	—	20	ns	
		Input			—	1	µs	
	Slave access time		2.7 V or above	t_{SA}	—	6	t_{Pcyc}	Figure 5.51, Figure 5.52
			1.8 V or above		—	7		
	Slave output release time		2.7 V or above	t_{REL}	—	5	t_{Pcyc}	
			1.8 V or above		—	6		

Note 1. t_{Pcyc}: PCLK cycle
Note 2. N: An integer from 1 to 8 that can be set by the RSPI clock delay register (SPCKD)
Note 3. N: An integer from 1 to 8 that can be set by the RSPI slave select negation delay register (SSLND)

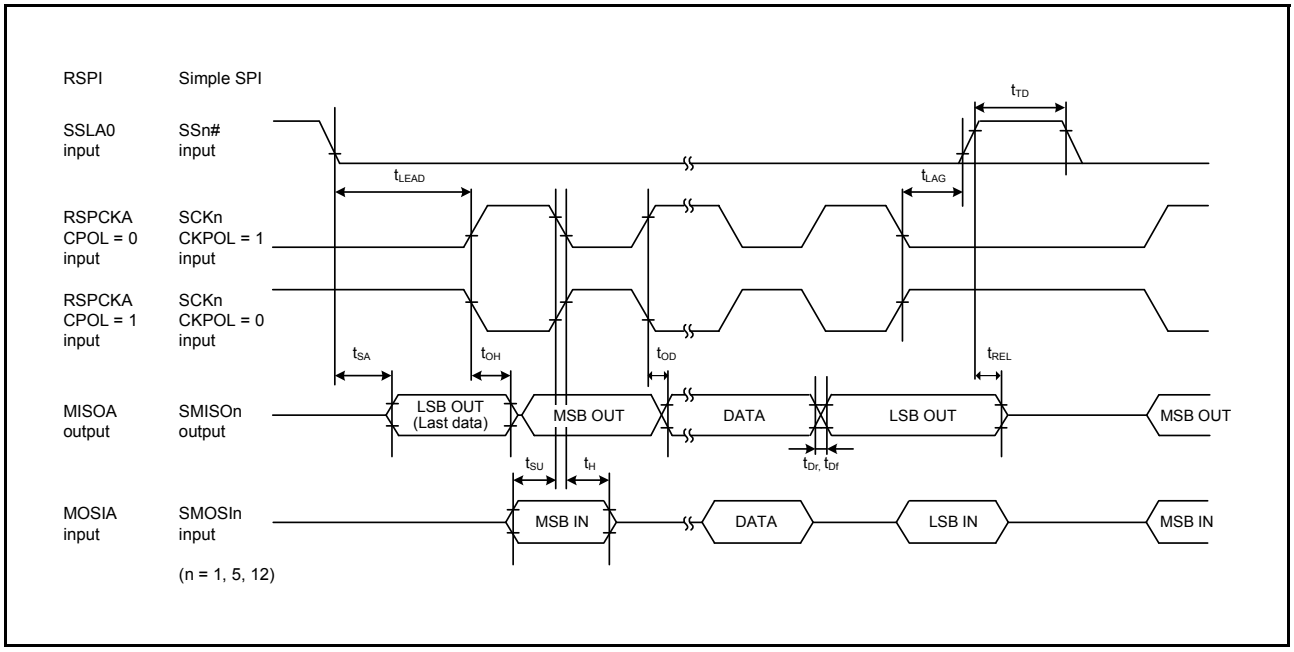
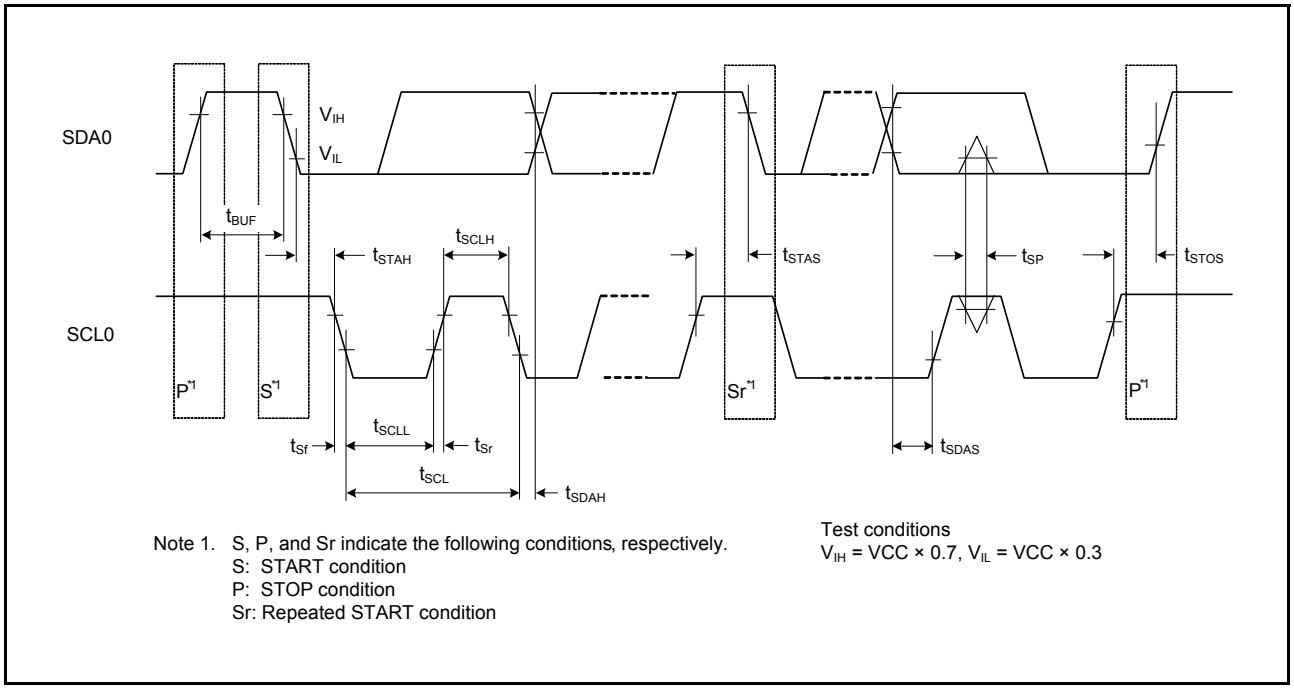


Figure 5.52 RSPI Timing (Slave, CPHA = 1) and Simple SPI Timing (Slave, CKPH = 0)



Note 1. S, P, and Sr indicate the following conditions, respectively.
S: START condition
P: STOP condition
Sr: Repeated START condition

Test conditions
V_{IH} = VCC × 0.7, V_{IL} = VCC × 0.3

Figure 5.53 RIIC Bus Interface Input/Output Timing and Simple I²C Bus Interface Input/Output Timing

Table 5.41 A/D Converter Channel Classification

Classification	Channel	Conditions	Remarks
High-precision channel	AN000 to AN004, AN006	AVCC0 = 1.8 to 3.6 V	Pins AN000 to AN004 and AN006 cannot be used as digital outputs when the A/D converter is in use.
Normal-precision channel	AN008 to AN015		
Internal reference voltage input channel	Internal reference voltage	AVCC0 = 2.0 to 3.6 V	
Temperature sensor input channel	Temperature sensor output	AVCC0 = 2.0 to 3.6 V	

Table 5.42 A/D Internal Reference Voltage Characteristics

Conditions: 2.0 V ≤ VCC = VCC_USB ≤ 3.6 V, 2.0 V ≤ AVCC0 ≤ 3.6 V*1, VSS = AVSS0 = VREFL0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item	Min.	Typ.	Max.	Unit	Test Conditions
Internal reference voltage input channel*2	1.36	1.43	1.50	V	

Note 1. The internal reference voltage cannot be selected for input channels when AVCC0 < 2.0 V.
Note 2. The A/D internal reference voltage indicates the voltage when the internal reference voltage is input to the A/D converter.

5.6 D/A Conversion Characteristics

Table 5.43 D/A Conversion Characteristics

Conditions: 1.8 V ≤ VCC = VCC_USB ≤ 3.6 V, 1.8 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, fPCLKB ≤ 32 MHz, T_a = –40 to +105°C

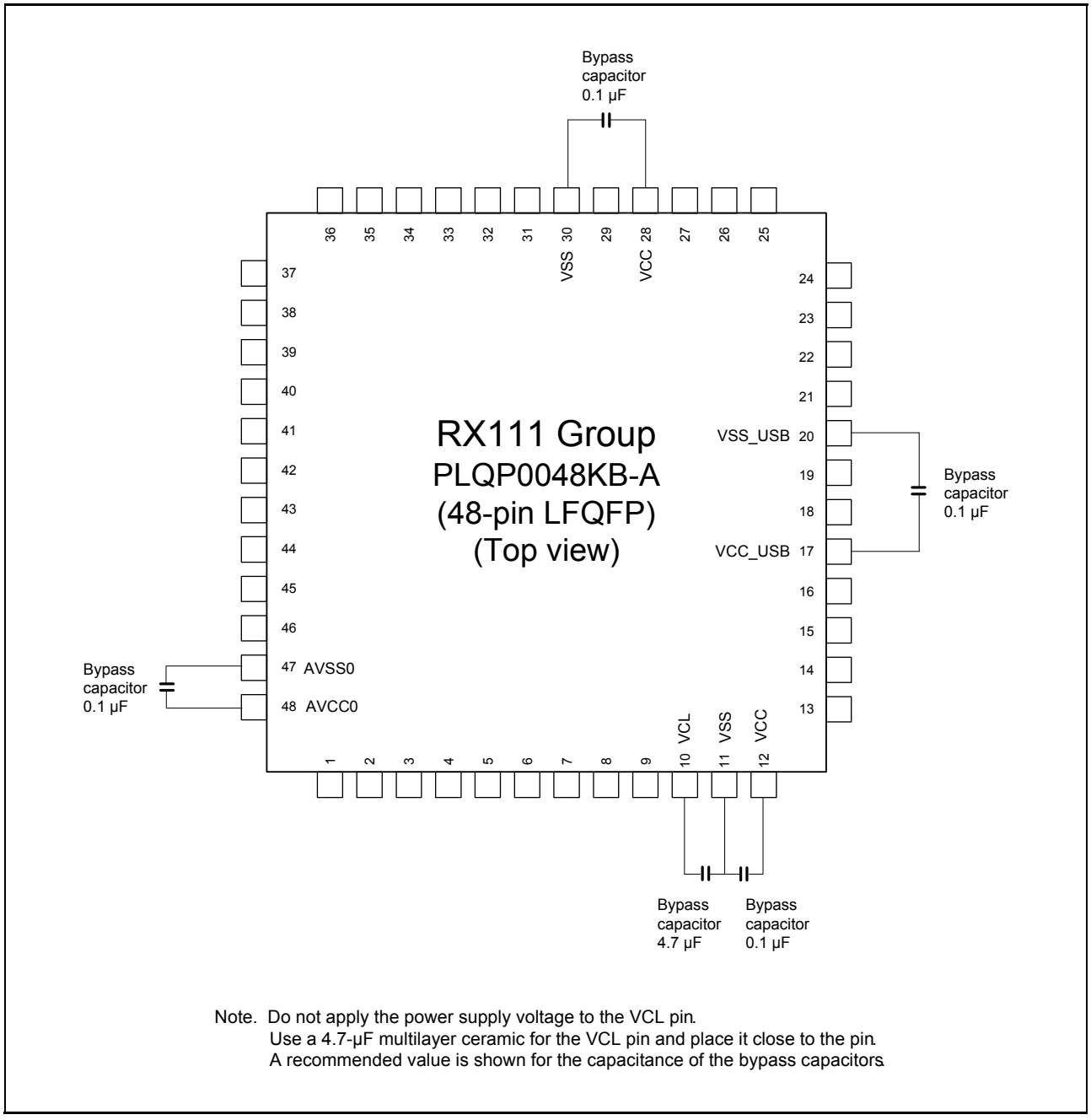
Item		Min.	Typ.	Max.	Unit	Test Conditions
Resolution		—	—	8	Bit	
Conversion time	VCC = 2.7 to 3.6 V	—	—	3.0	µs	35-pF capacitive load
	VCC = 1.6 to 2.7 V	—	—	6.0		
Absolute accuracy	VCC = 2.4 to 3.6 V	—	—	±3.0	LSB	2-MΩ resistive load
	VCC = 1.8 to 2.4 V	—	—	±3.5		
	VCC = 2.4 to 3.6 V	—	—	±2.0	LSB	4-MΩ resistive load
	VCC = 1.8 to 2.4 V	—	—	±2.5		
RO output resistance		—	6.4	—	kΩ	

5.7 Temperature Sensor Characteristics

Table 5.44 Temperature Sensor Characteristics

Conditions: 2.0 V ≤ VCC = VCC_USB ≤ 3.6 V, 2.0 V ≤ AVCC0 ≤ 3.6 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

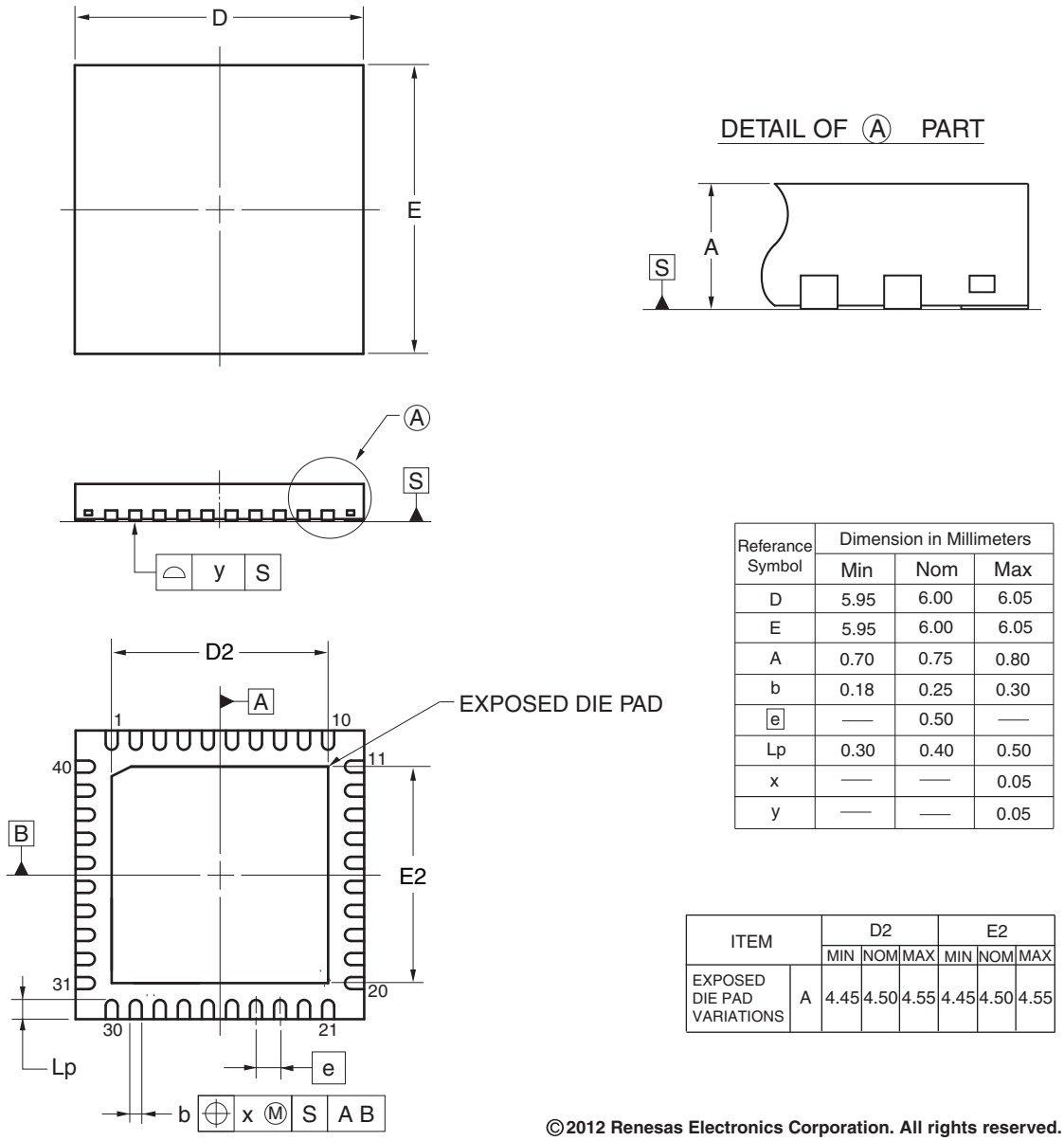
Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Relative accuracy	—	—	±1.5	—	°C	2.4 V or above
		—	±2.0	—		Below 2.4 V
Temperature slope	—	—	–3.65	—	mV/°C	
Output voltage (at 25°C)	—	—	1.05	—	V	VCC = 3.3 V
Temperature sensor start time	t_{START}	—	—	5	µs	
Sampling time	—	5	—	—	µs	



Note. Do not apply the power supply voltage to the VCL pin.
Use a 4.7-µF multilayer ceramic for the VCL pin and place it close to the pin.
A recommended value is shown for the capacitance of the bypass capacitors.

Figure 5.64 Connecting Capacitors (48-pin LFQFP)

JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-HWQFN40-6x6-0.50	PWQN0040KC-A	P40K8-50-4B4-4	0.09



Referance Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	5.95	6.00	6.05
E	5.95	6.00	6.05
A	0.70	0.75	0.80
b	0.18	0.25	0.30
e	—	0.50	—
Lp	0.30	0.40	0.50
x	—	—	0.05
y	—	—	0.05

ITEM		D2			E2		
		MIN	NOM	MAX	MIN	NOM	MAX
EXPOSED DIE PAD VARIATIONS	A	4.45	4.50	4.55	4.45	4.50	4.55

Figure F 40-Pin HWQFN (PWQN0040KC-A)

REVISION HISTORY	RX111 Group Datasheet

Rev.	Date	Description	
		Page	Summary
0.60	Apr 15, 2013	—	First edition, issued
0.90	May 15, 2013	Features	
		1	Changed
		1. Overview	
		2 to 4	Table 1.1 Outline of Specifications changed
		10 to 12	Table 1.4 Pin Functions changed
		13	Figure 1.3 Pin Assignments of the 64-Pin LQFP changed
		14	Figure 1.4 Pin Assignments of the 64-Pin WFLGA changed
		15	Figure 1.5 Pin Assignments of the 48-Pin LQFP/HWQFN changed
		18, 19	Table 1.5 List of Pins and Pin Functions (64-Pin LQFP) changed, Note 1 added
		20, 21	Table 1.6 List of Pins and Pin Functions (64-Pin WFLGA) changed, Note 1 added
		22, 23	Table 1.7 List of Pins and Pin Functions (48-Pin LQFP/HWQFN) changed, Note 1 added
		24, 25	Table 1.8 List of Pins and Pin Functions (40-Pin HWQFN) changed, Note 1 added
		26	Table 1.9 List of Pins and Pin Functions (36-Pin WFLGA) changed, Note 1 added
		4. I/O Registers	
		33 to 48	Table 5.1 List of I/O Registers (Address Order) changed
1.00	Jun 19, 2013	1. Overview	
		9	Figure 1.2 Block Diagram changed
		20, 21	Table 1.6 List of Pins and Pin Functions (64-Pin WFLGA) changed
		26	Table 1.9 List of Pins and Pin Functions (36-Pin WFLGA) changed
		4. I/O Registers	
		33 to 48	Table 4.1 List of I/O Registers (Address Order) changed
		5. Electrical Characteristics	
		49 to 99	Added
1.20	Sep 29, 2014	1. Overview	
		2 to 4	Table 1.1 Outline of Specifications: ROM capacity and RAM capacity changed, Unique ID added
		6, 7	Table 1.3 List of Products, changed
		8	Figure 1.1 How to Read the Product Part No., Memory Capacity, and Package Type, changed
		9	Figure 1.2 Block Diagram changed
		10	Table 1.4 Pin Functions changed
		15	Figure 1.5 Pin Assignments of the 48-Pin LFQFP/HWQFN: Note added
		16	Figure 1.6 Pin Assignments of the 40-Pin HWQFN: Note added
		3. Address Space	
		30	Figure 3.1 Memory Map, changed
		4. I/O Registers	
		33 to 48	Table 4.1 List of I/O Registers (Address Order), changed
		5. Electrical Characteristics	
		49	Table 5.1 Absolute Maximum Ratings, Table 5.2 Recommended Operating Conditions, changed
		50	Table 5.3 DC Characteristics (1) and Table 5.4 DC Characteristics (2), changed
		51	Table 5.5 DC Characteristics (3), changed
		55, 56	Table 5.8 DC Characteristics (6), added
		56	Table 5.9 DC Characteristics (7), changed
		58	Table 5.10 DC Characteristics (8), added
		59	Table 5.13 DC Characteristics (11), changed
		61	Table 5.19 Output Values of Voltage (1) and Table 5.20 Output Values of Voltage (2), changed
		68	Table 5.22 Operation Frequency Value (Middle-Speed Operating Mode) changed, Note 4 added
		69	Table 5.24 Clock Timing, changed
		78	Table 5.32 Timing of On-Chip Peripheral Modules (1) changed
		81	Table 5.35 Timing of On-Chip Peripheral Modules (4), changed
		82	Table 5.36 Timing of On-Chip Peripheral Modules (5): Note 2 deleted
		83	Figure 5.37 SCK Clock Input Timing changed
		84	Figure 5.38 SCI Input/Output Timing: Clock Synchronous Mode changed

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